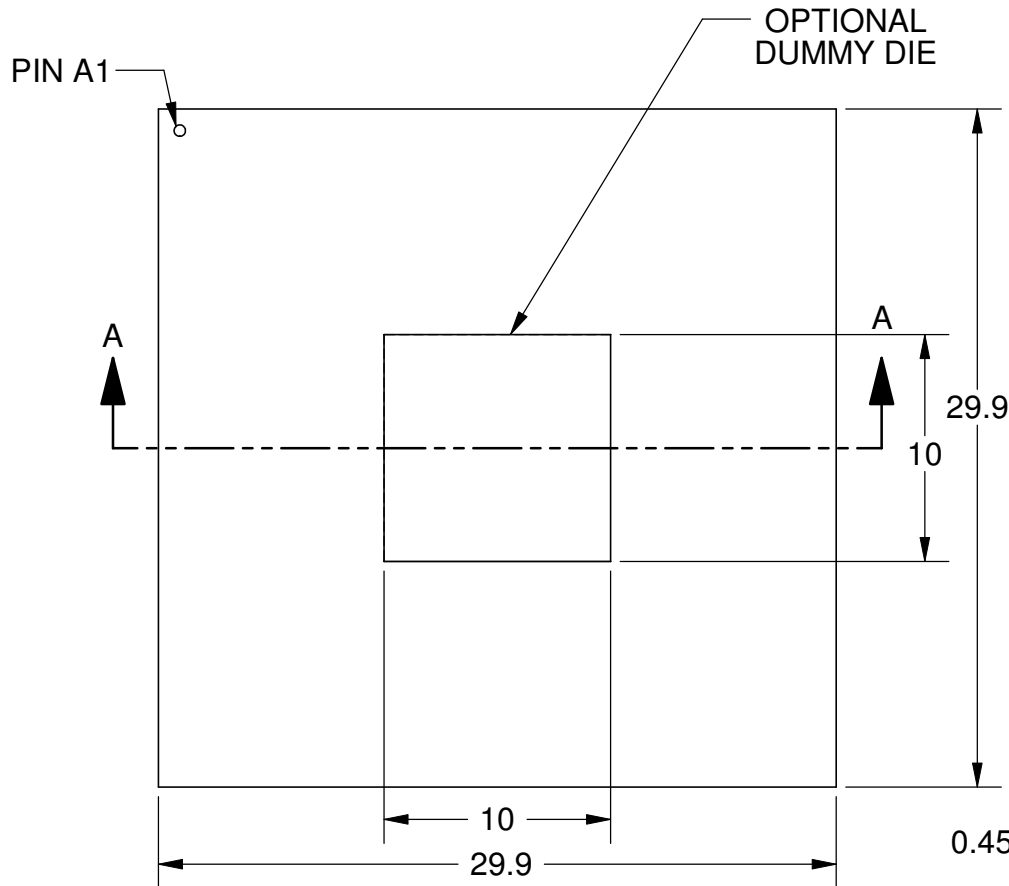
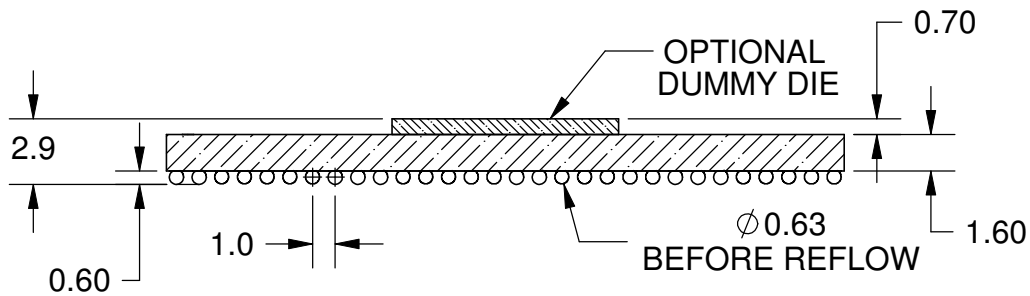
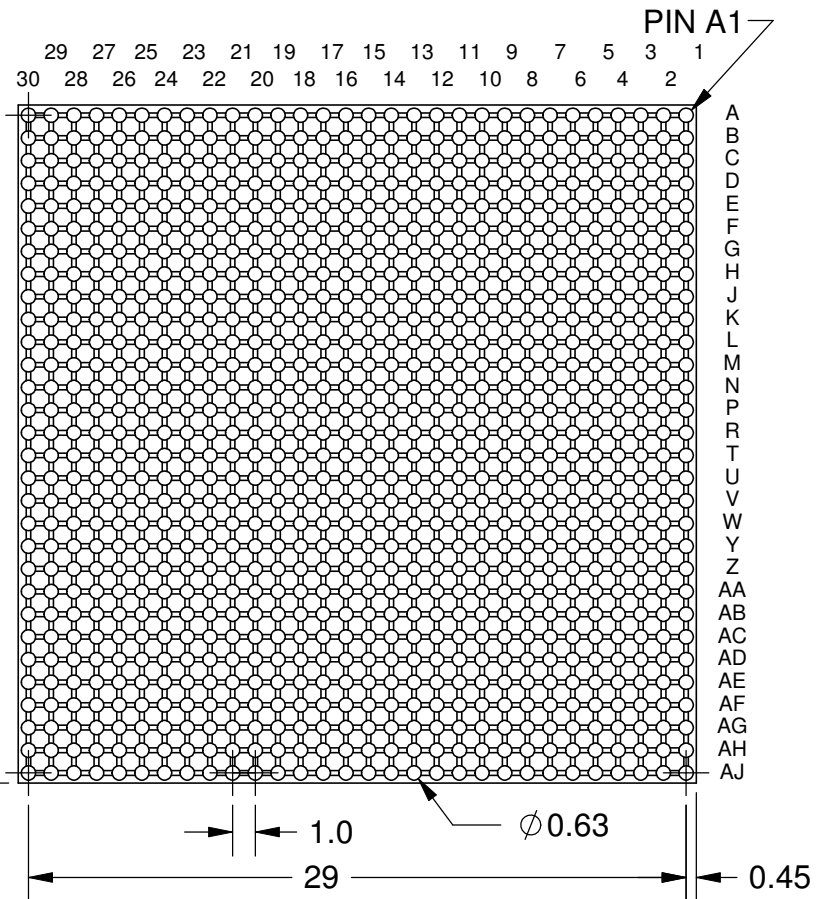


TOP VIEW



BALL VIEW




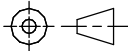
SECTION A-A

PART NUMBER TABLE

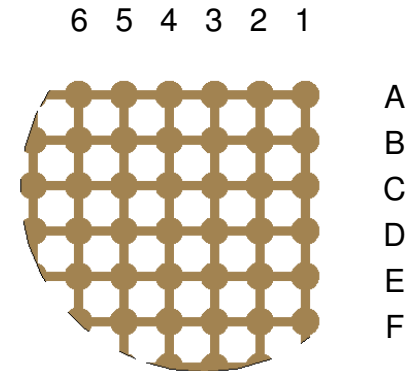
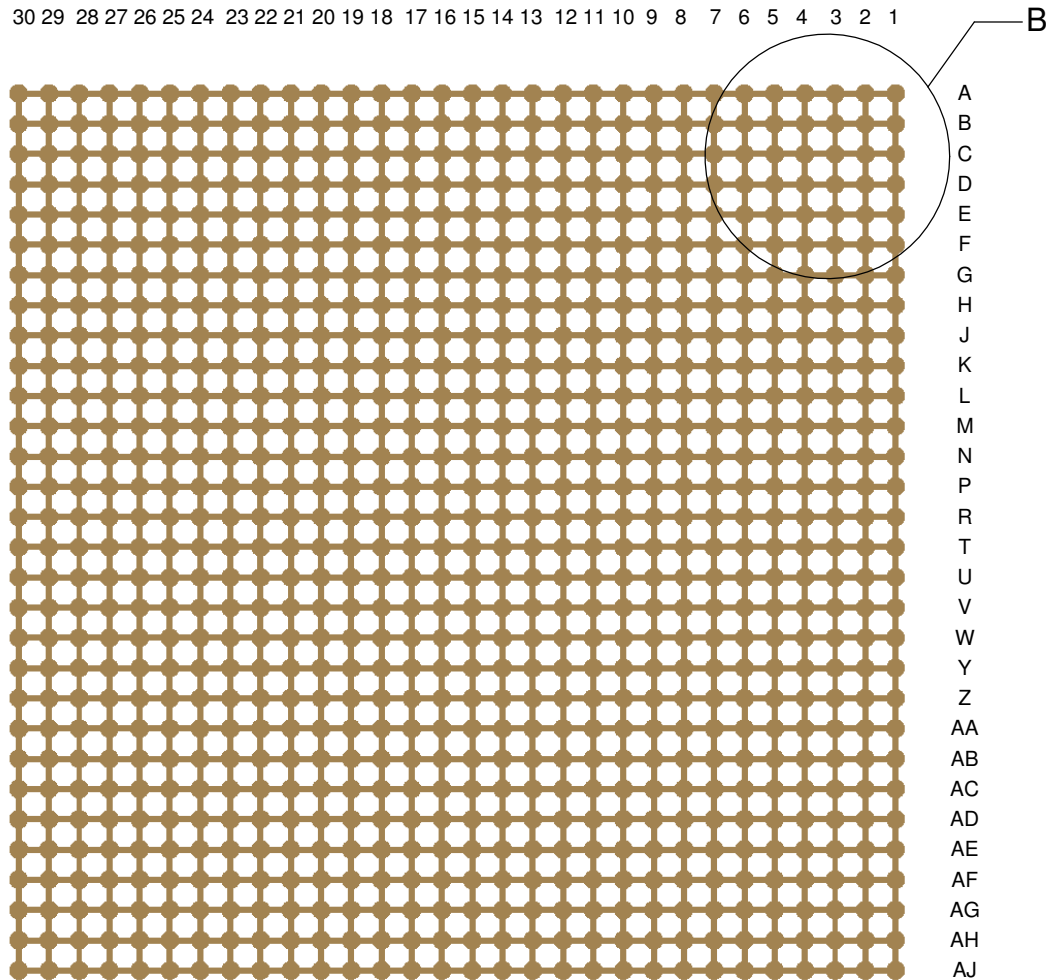
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
LBGA900T1.0C-BUS	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LBGA900T1.0C-BUS-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LBGA900T1.0-BUS	Sn63/Pb37	NO	NO	NO
LBGA900T1.0-BUS-D	Sn63/Pb37	NO	NO	YES

Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.635mm [25 MIL].
- 4) SOLDER MASK DEFINED PAD OPENING: 0.508mm [20 MIL].
- 5) PAD Cu DIAMETER: 0.685mm [27 MIL].
- 6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

TOLERANCE UNLESS NOTED		APPROVALS		DATE					
X.XX	+/- 0.01	DRAWN	J. Hines	11/21/2014					TITLE LBGA900T1.0-BUS ALL PADS SHORTED
X.XXX	+/- 0.005	ENG	M. Hart	11/21/2014					
X.XXXX	+/- 0.0005	MFG			SCALE		SIZE	DRAWING NO.	REV
ANGLES +/- 0.5° ALL DIMENSIONS IN <input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		THIRD ANGLE PROJECTION 			3:1	A	513001	A	
REVISED		DO NOT SCALE DRAWING			SHEET 1 OF 3				

BALL VIEW



DETAIL B
SCALE 6 : 1

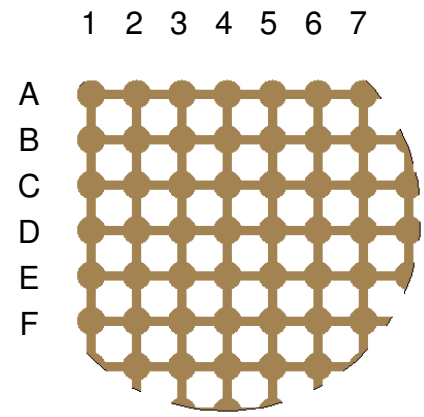
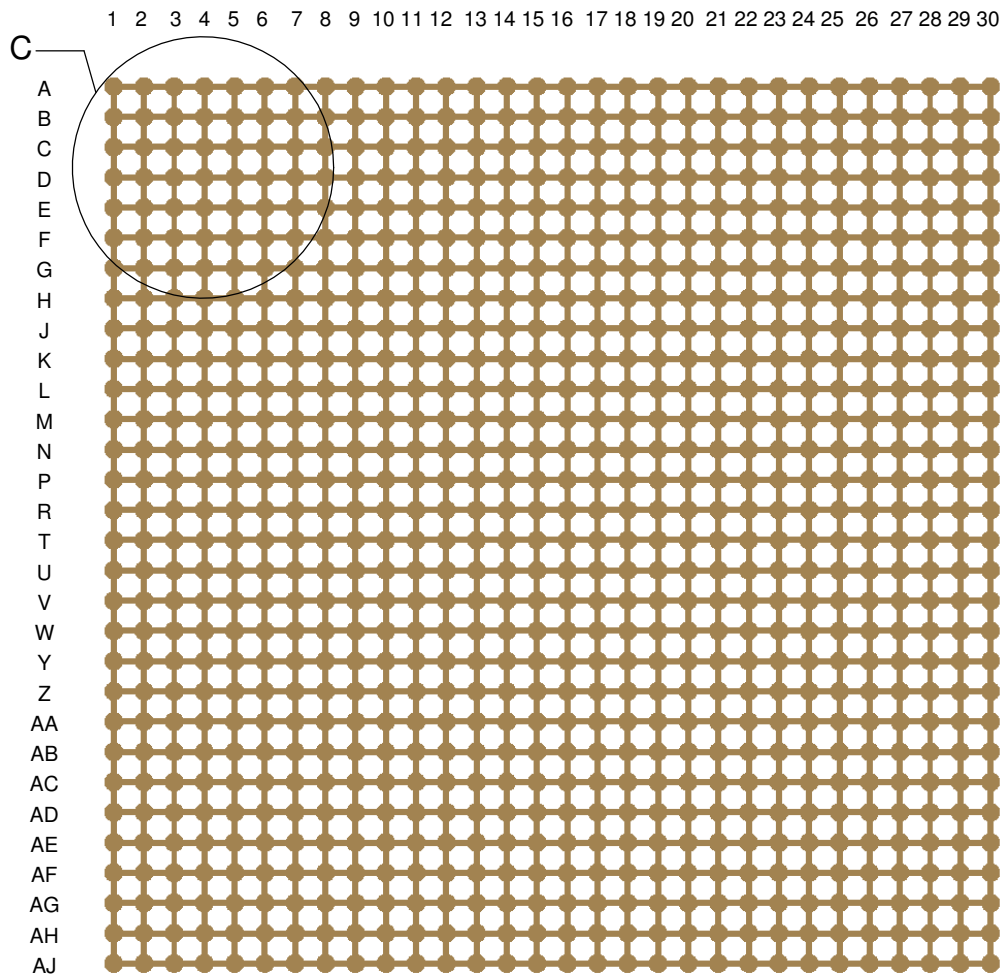
ALL PADS
CONNECTED

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.685mm [27 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.204mm [8 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.508mm [20 MIL].

TopLine ®			
TITLE		LPGA900T1.0-BUS ALL PADS SHORTED	
SCALE	SIZE	DRAWING NO.	REV
4:1	A	513001	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

BOTTOM SIDE (TOP X-RAY VIEW)



DETAIL C
SCALE 6 : 1

ALL PADS
CONNECTED

TopLine ®			
TITLE LPGA900T1.0-BUS ALL PADS SHORTED			
SCALE 4:1	SIZE A	DRAWING NO. 513001	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 3	